

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2016	(257/734).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:00
L2	3014	(257/737).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:01
L3	631	(257/735).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:01
L4	268	(257/736).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:02
L5	1255	solder adj bump and plastic and electrode and surface.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2008/10/01 10:03
L6	260	deformed and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2008/10/01 10:04
L7	2062	(257/e21.506).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:04
L8	927	(438/121).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:05
L9	1400	(257/779).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:09

L10	418	(257/674).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:37
L11	1	("7312519").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:39
L12	3181	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:44
L13	2438	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:45
L14	1821	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:46
L15	510	(257/E23.141).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 10:46
L16	12	STACKED AND PACKAGE AND SUBSTRATE AND ENCAPSULATION AND TOP ADJ SIDE AND SPACE.CLM.	US-PGPUB	OR	OFF	2008/10/01 10:48
L17	1454	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 11:05
L18	1164	(257/414).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 11:35
L19	1162	(257/415).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 11:41

L20	349	(257/416).OCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 11:42
L21	0	MEMES AND SEMI CONDUCTOR ADJ SUBSTRATE AND MIRROR.CLM.	US-PGPUB	OR	ON	2008/10/01 11:45
L22	341	MEMS AND SEMI CONDUCTOR ADJ SUBSTRATE AND MIRROR.CLM.	US-PGPUB	OR	ON	2008/10/01 11:45
L23	329	(257/83).OCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 12:11
L24	0	PHOTODIODE AND EUTECTIC ADJ BONDING AND METALLIZATION. CLM.	US-PGPUB	OR	ON	2008/10/01 12:21
L25	0	PHOTODIODE AND EUTECTIC ADJ MIXTURE AND METALLIZATION. CLM.	US-PGPUB	OR	ON	2008/10/01 12:21
L26	0	PHOTODIODE AND EUTECTIC ADJ MIXTURE AND METALLIZATION. CLM.	US-PGPUB	OR	ON	2008/10/01 12:21
L27	2	PHOTODIODE AND EUTECTIC ADJ MIXTURE CLM.	US-PGPUB	OR	ON	2008/10/01 12:22
L28	139	(257/E31.058).OCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2008/10/01 12:23

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